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## 一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

frxelec



5. Abol e Ma im m Ra ing (Ta=25 )

Pa ame e		S mbol	Ra ed Val e	Uni

6. Electrical Optical Characteristics at  $T_a=25\text{ }^\circ\text{C}$

Parameter	Symbol	Min	T <sub>st</sub>	Max	Unit	Condition
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## 7. O de Info ma ion

Pa N mbe

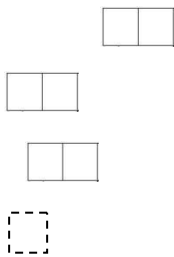
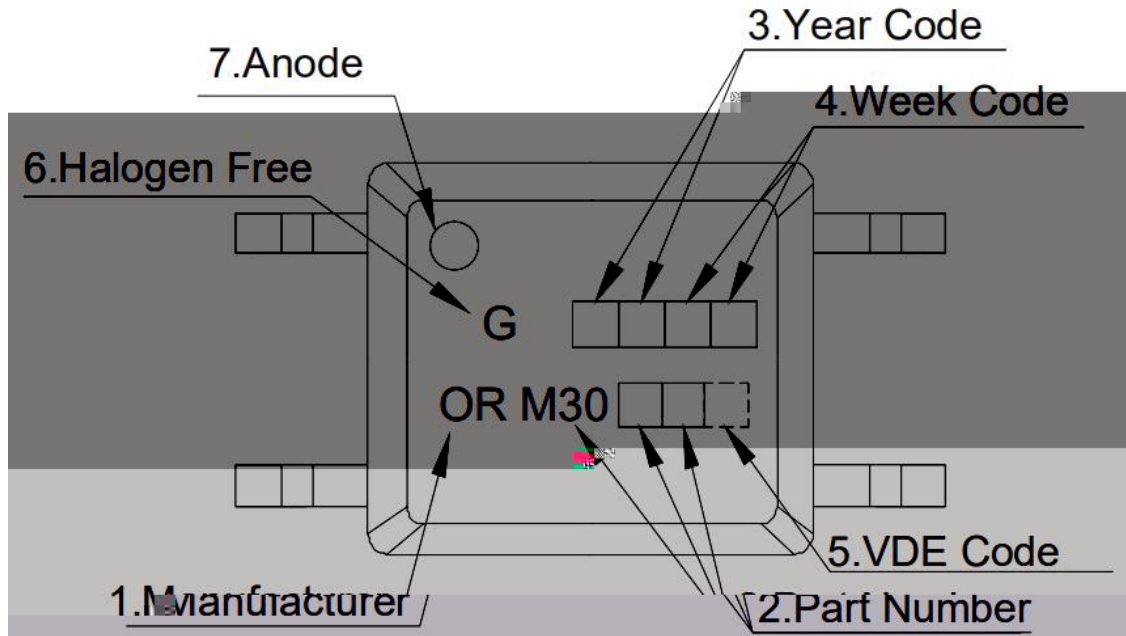
**OR-M302X-W-Y-Z**

**o OR-M305X-W-Y-Z**

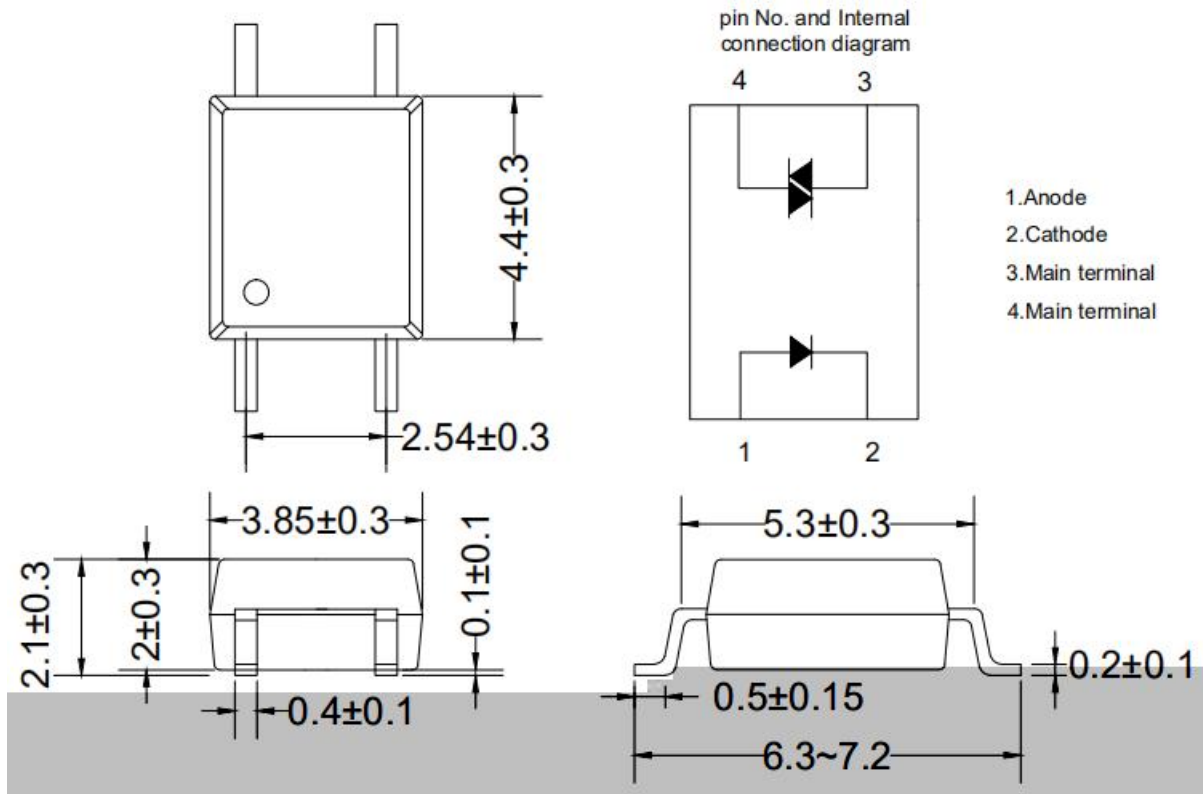
No e

O ion	De c i ion	Packing an i

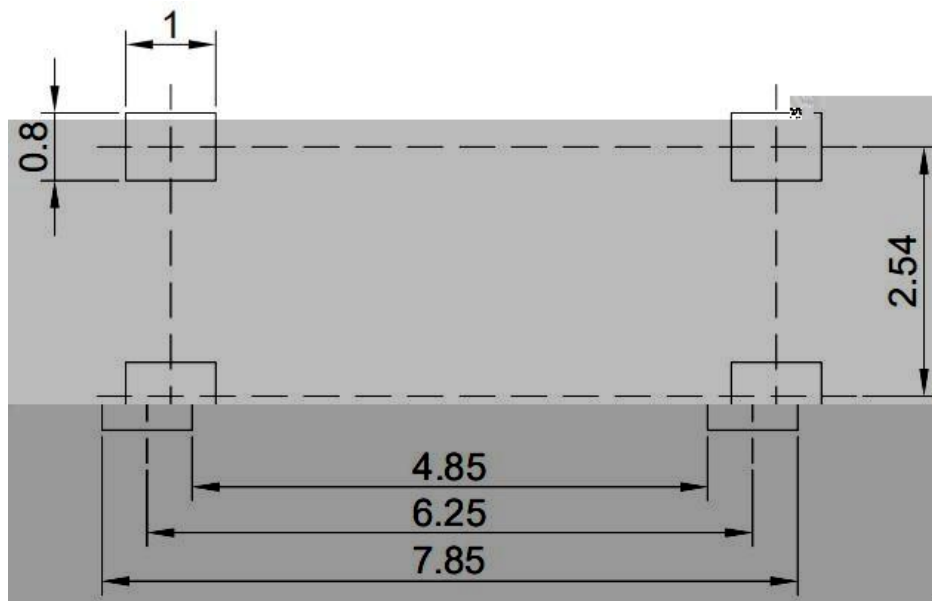
## 8. Naming Rule



### 9. Package Dimension

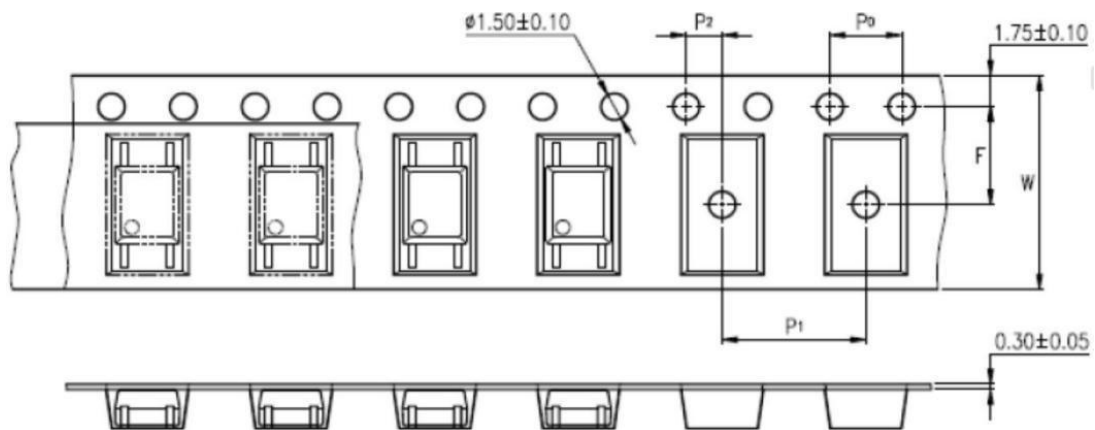
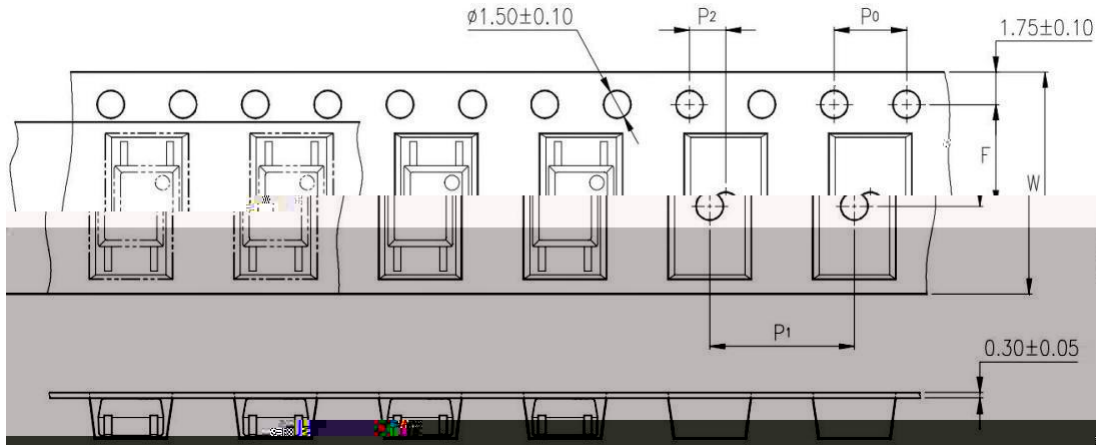


### 10. Recommended Foot Print in Package (Mo n Pad)



ni mm

### 11. Ta ing Dimen ion



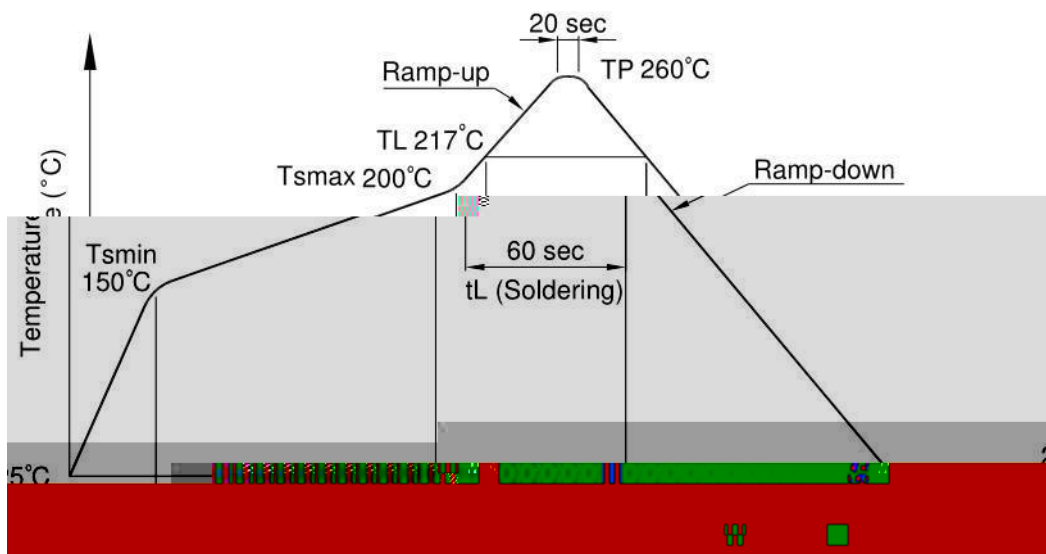






### 13. Temperature Profile Of Soldering

Profile Item	Condition






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## 14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

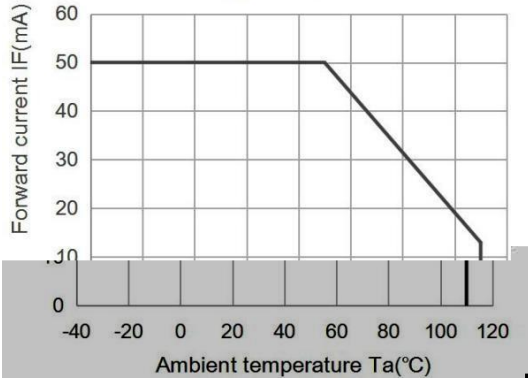


Fig.2 On-state current ITM (A) vs Ambient temperature

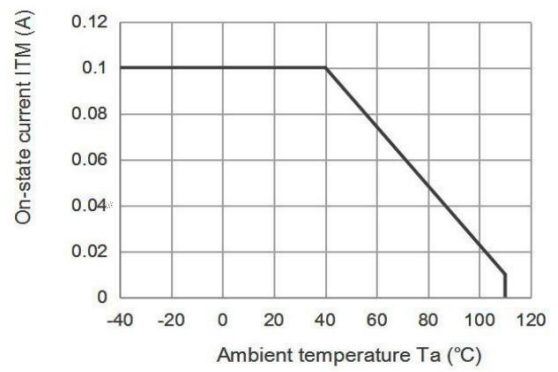


Fig.3 Minimum Trigger Current vs. Ambient temperature

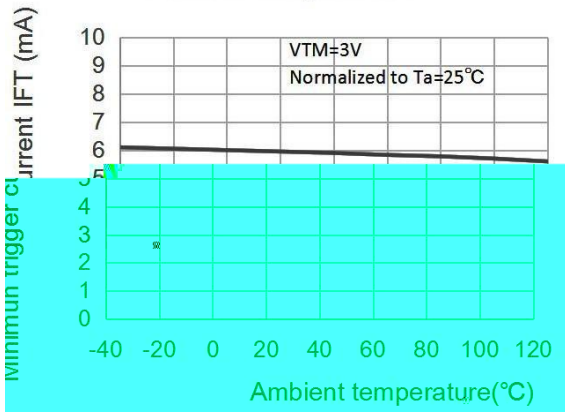


Fig.4 Forward current vs. Forward voltage

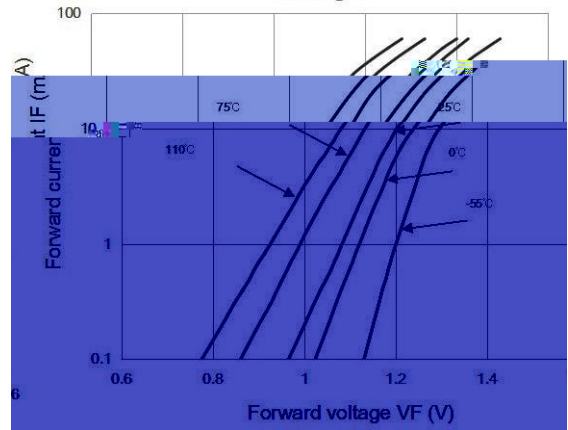


Fig.5 On-state voltage vs. Ambient temperature

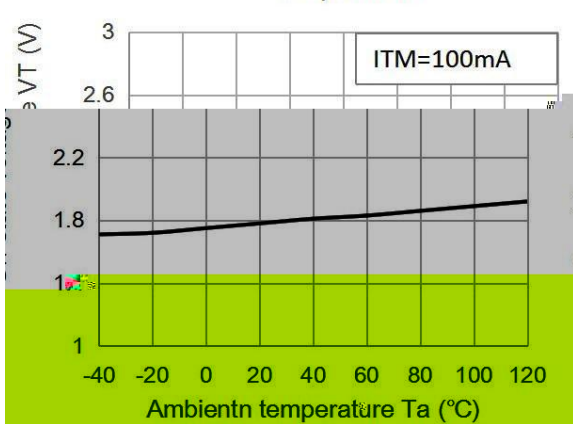


Fig.6 Holding current vs. Ambient temperature

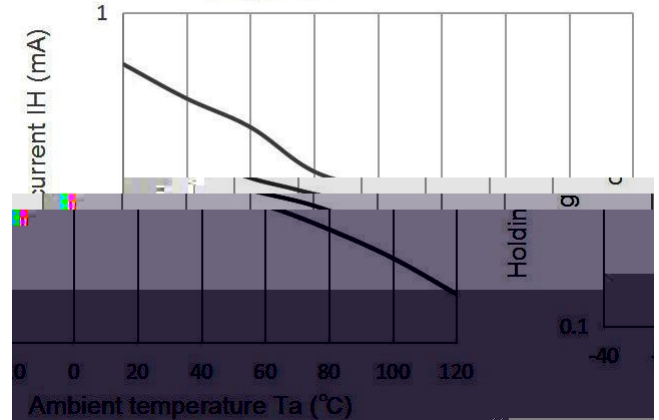


Fig.7 Repetitive peak off-state current vs. Temperature

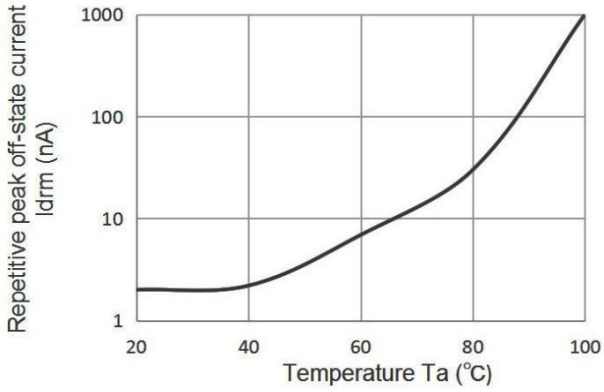
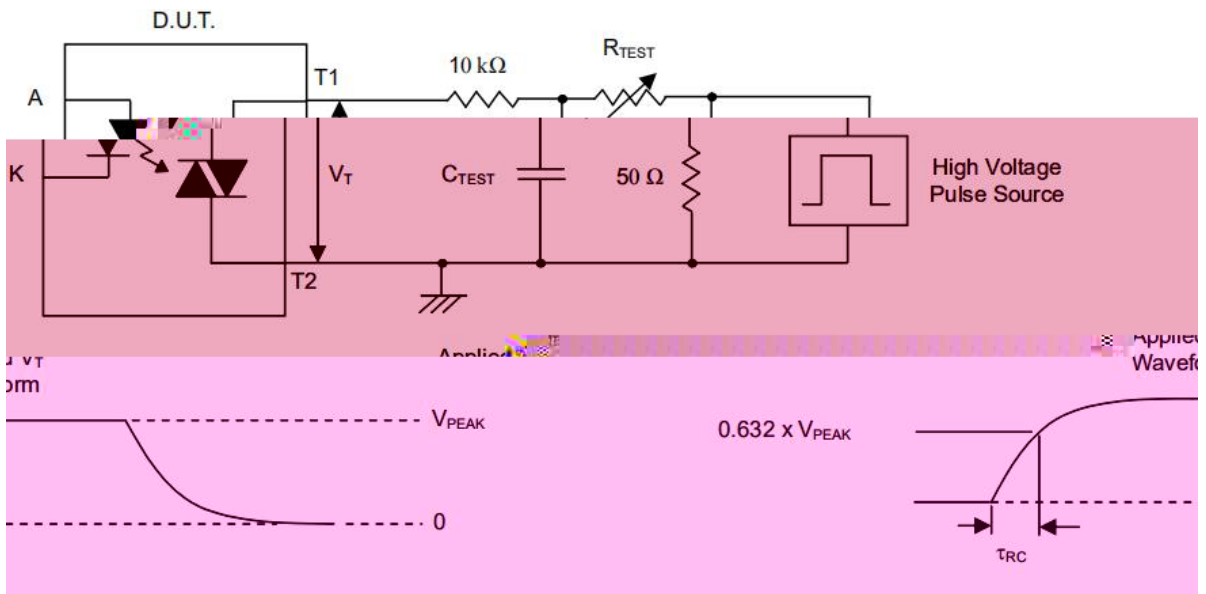
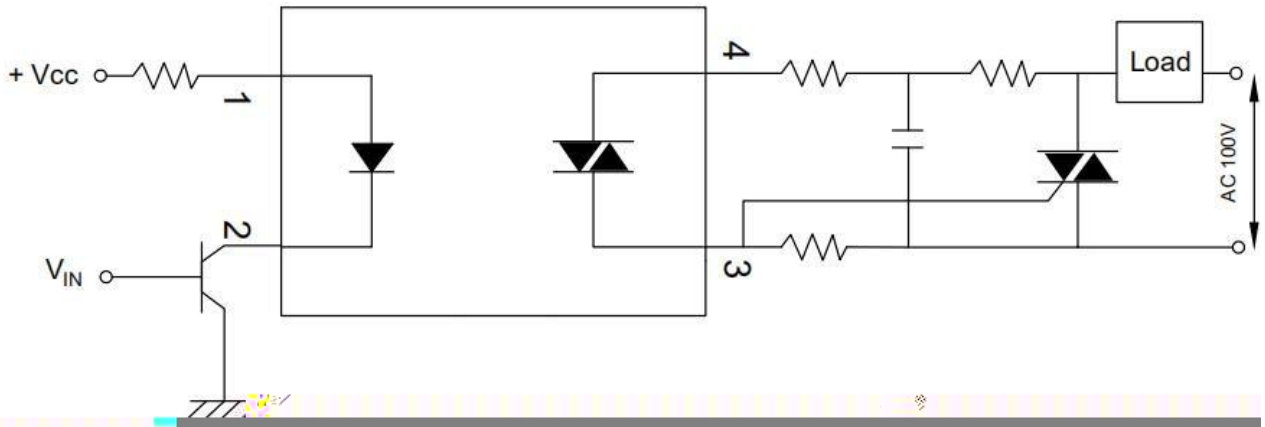
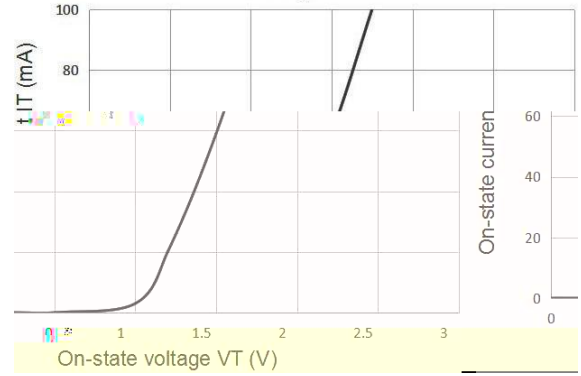


Fig.8 On-state current vs. On-state voltage



## Measurement Method

